



PLASMONIC NANOSENSORS FOR THz COMMUNICATION AND SENSING FOR IoT APPLICATIONS

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Presented at

**The 14th U.S.-Korea Forum on Nanotechnology: Internet of Things
(IoT) including Nanosensors and Neuromorphic Computing**



Outline

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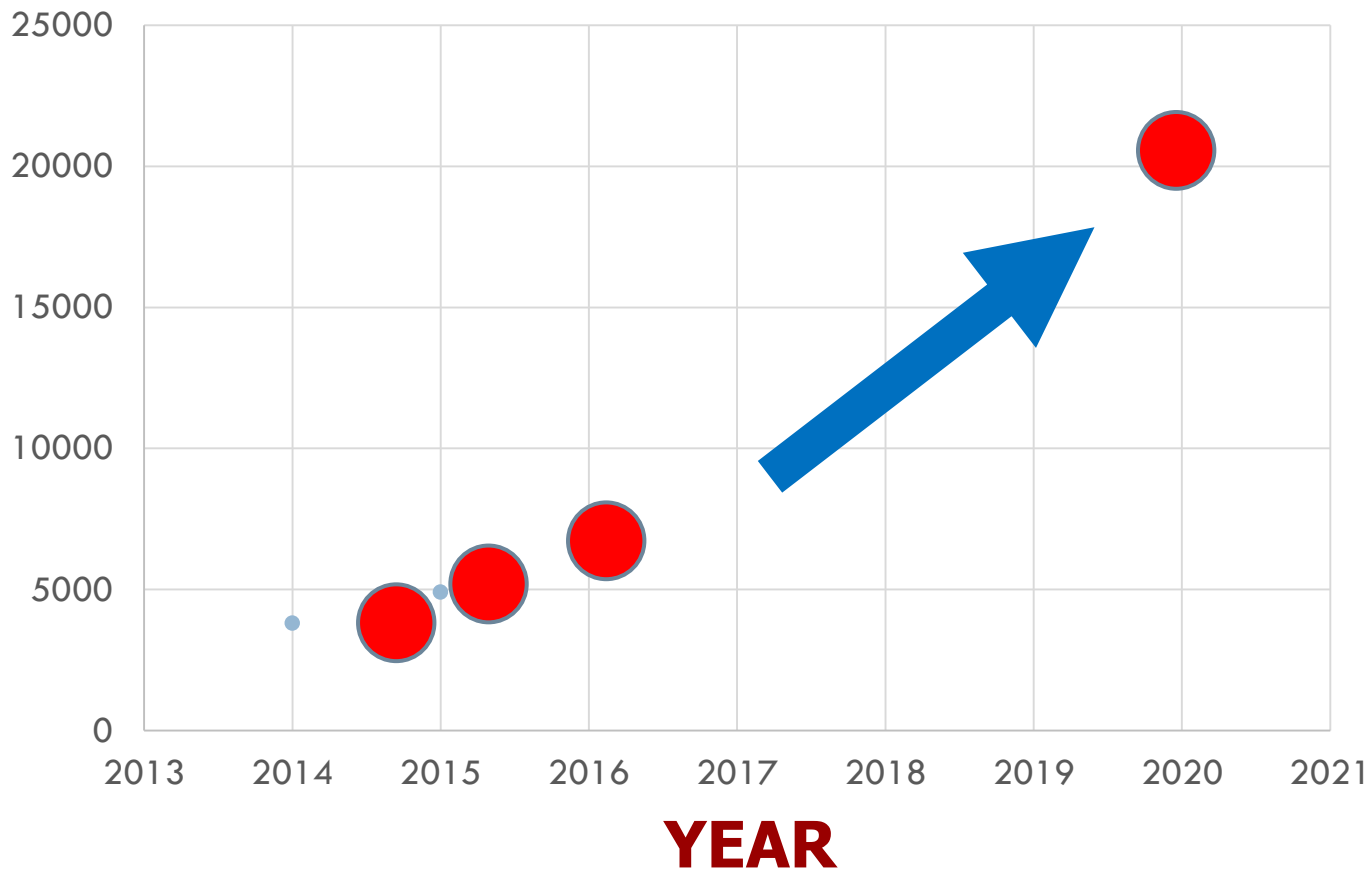
- **Motivation**
- **Scaling issues for VLSI**
- **THz communications on nanoscale**
- **Plasmonic Nanosensors**
- **CNT and graphene plasmonics on Si**
- **Future work**
- **Conclusions**

INTERNET OF THINGS INSTALLED BASE (MILLIONS OF UNITS)



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More aggressive estimates over 50 billions by 2020



DATA FROM <http://www.gartner.com/newsroom/id/3165317>



IoT needs

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- **LOW POWER WIDE AREA (LPWA) wireless technology**
- **Bandwidth**

IoT NEEDS



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**REQUIRE ADVANCED
NANOSCALE VLSI
TECHNOLOGY for ULTRA-
LOW POWER**

INTEL: 10 nm iPhone should be announced today

6

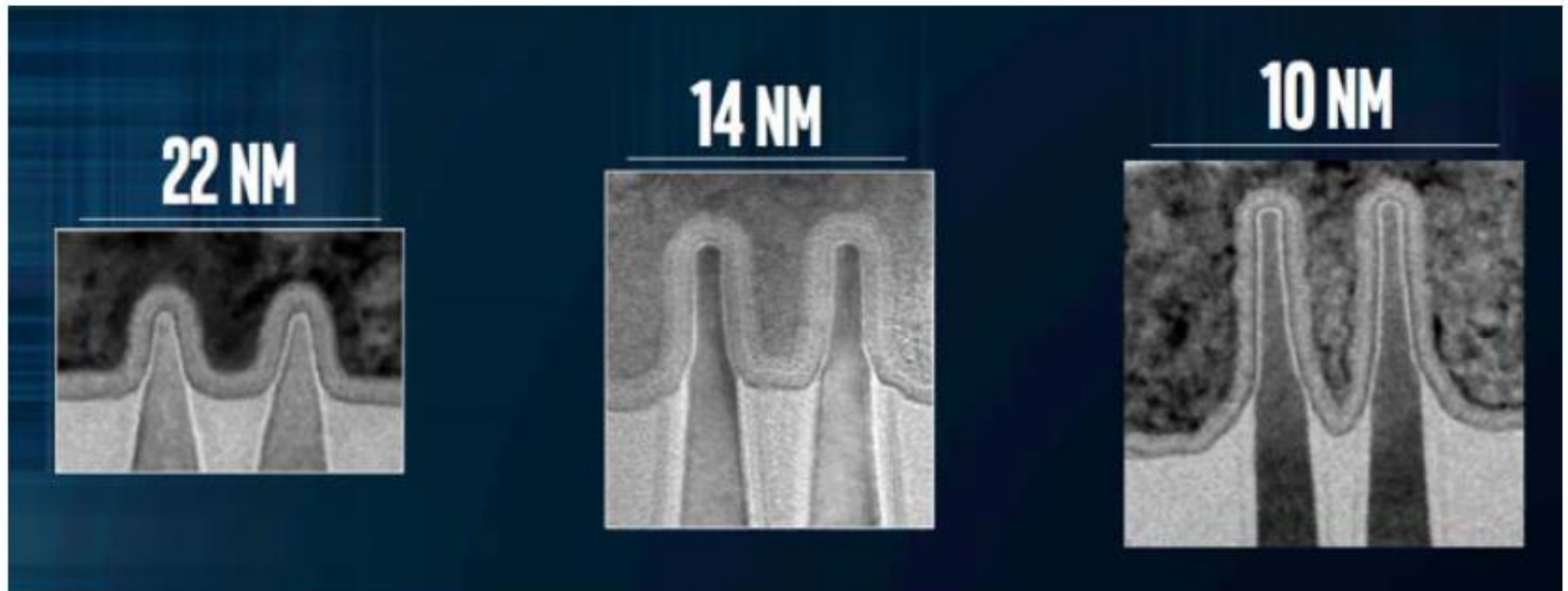


Image: Intel

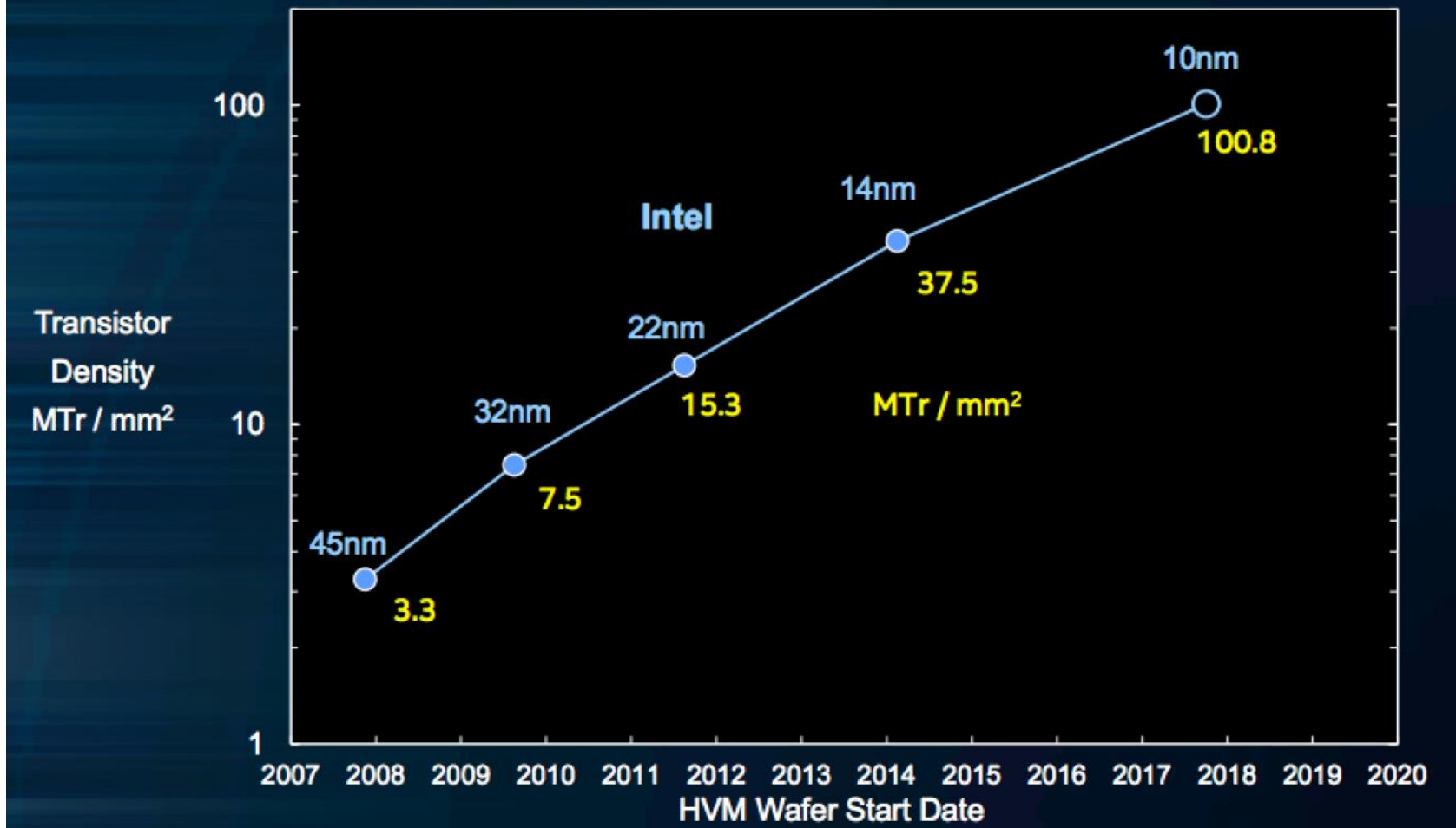
From Rachel Cortland, posted 30 March 2017

<https://spectrum.ieee.org/nanoclast/semiconductors/processors/intel-now-packs-100-million-transistors-in-each-square-millimeter>



0.1 billion transistors per mm²

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From Rachel Cortland, posted 30 March 2017

<https://spectrum.ieee.org/nanoclast/semiconductors/processors/intel-now-packs-100-million-transistors-in-each-square-millimeter>



5 nm?

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Metrology Research Engineer

GLOBALFOUNDRIES

Albany, NY, US

📅 Posted 60 days ago

Essential Responsibilities :

- Establishing overlay and CD measurement capabilities for the 7-nm node and beyond

Minimum Transistor size

9

Silicon unit cell 0.543 nm (9 unit cells for 5 nm)

Silicon –Silicon Dioxide interface 0.7 nm

Silicon-Silicon Dioxide layer 1 nm

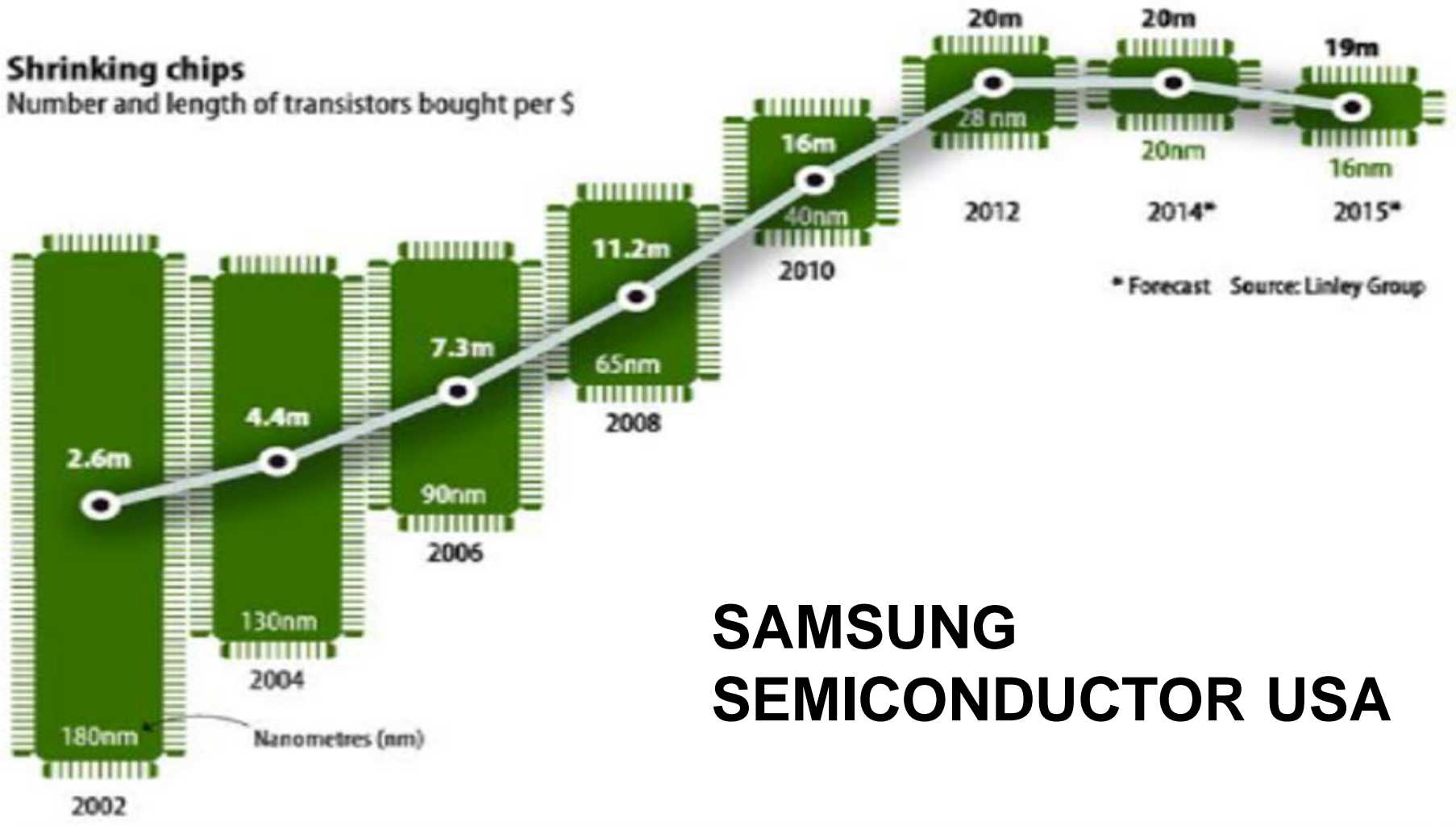


Ferdinand Hodler, Swiss (March 14, 1853 – May 19, 1918)

Cost technology rising after 28 nm

Shrinking chips

Number and length of transistors bought per \$



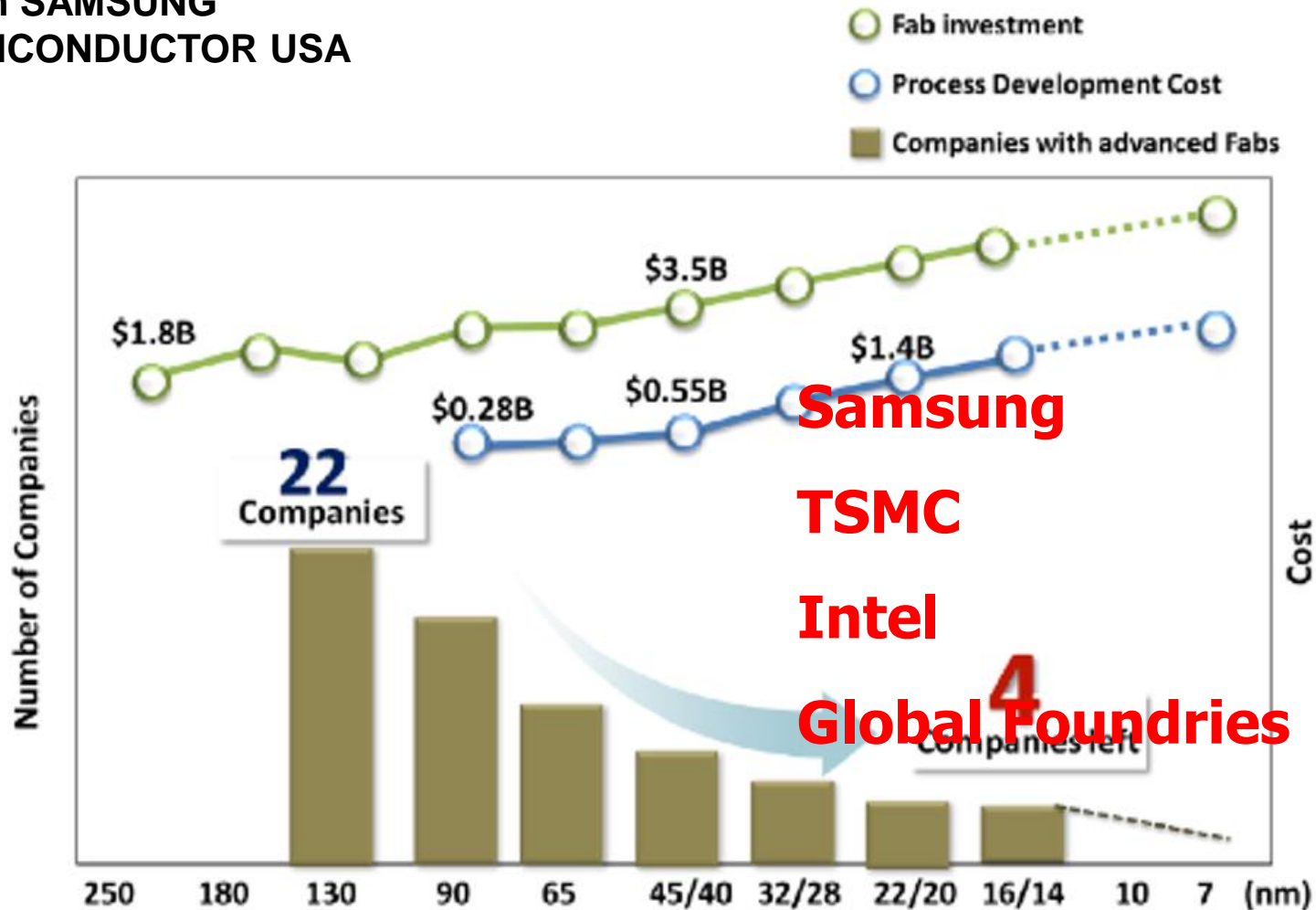
**SAMSUNG
SEMICONDUCTOR USA**



Companies dropping out

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From SAMSUNG
SEMICONDUCTOR USA

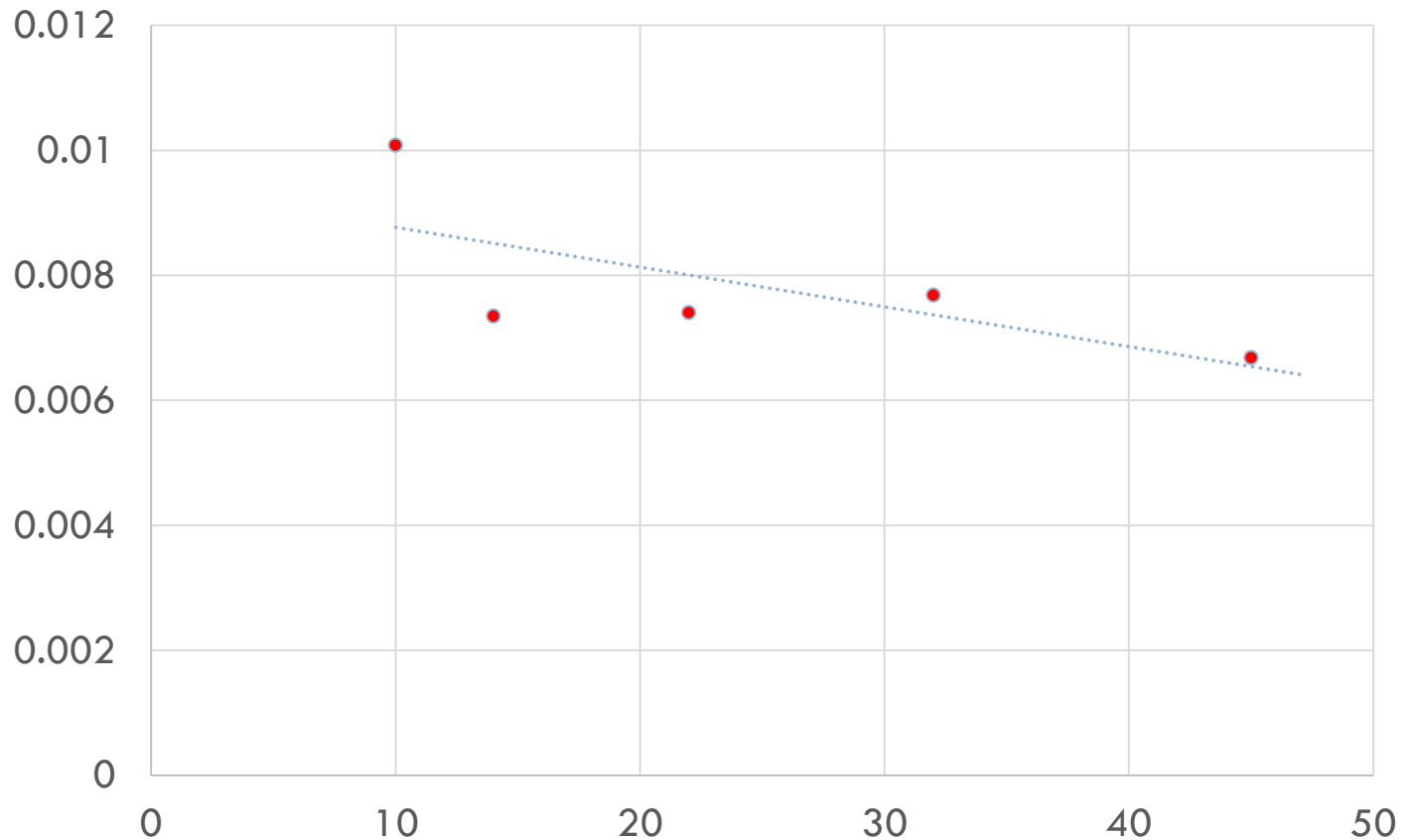


Area Efficiency for INTEL technology



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Area Efficiency

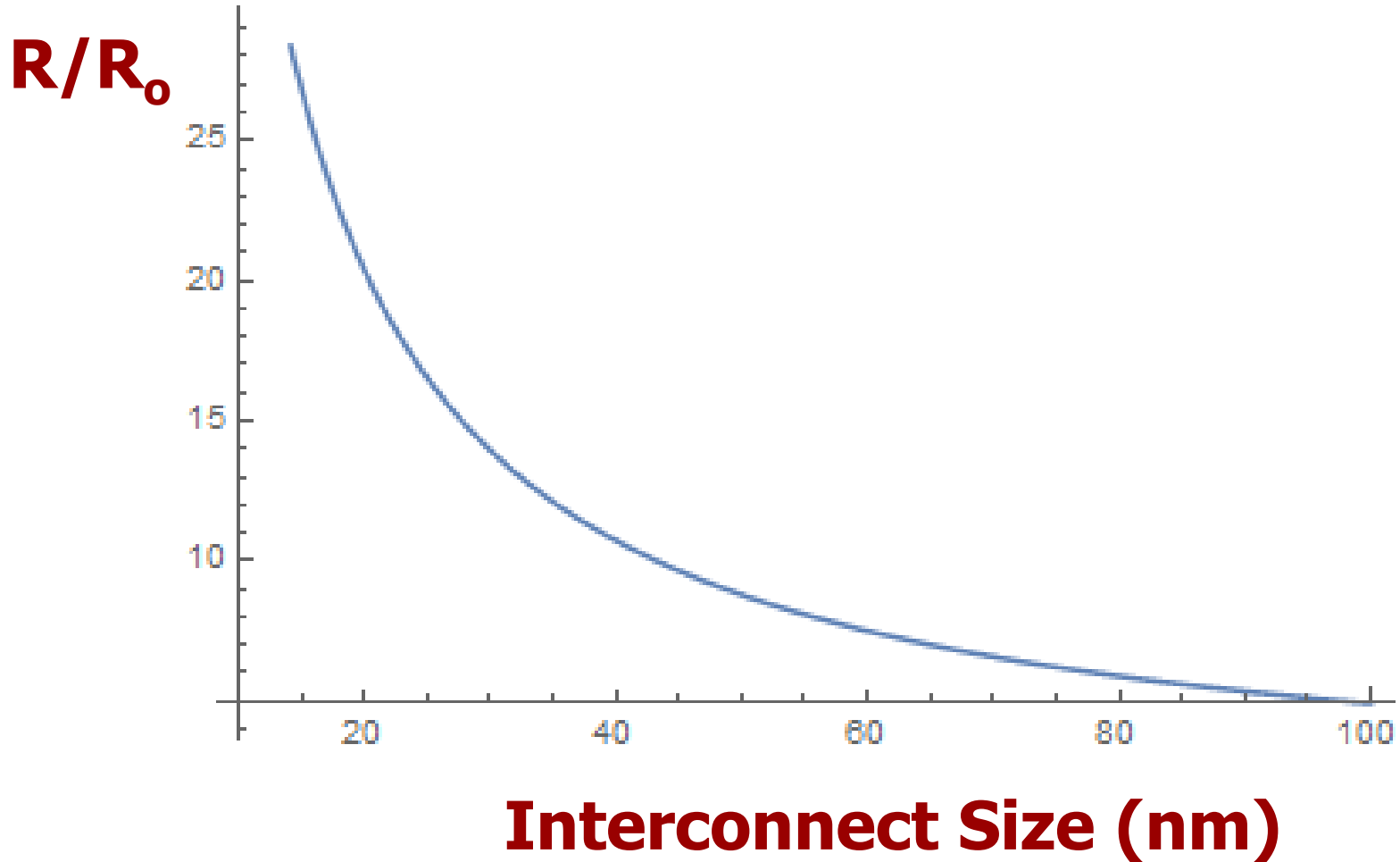


Feature size (nm)



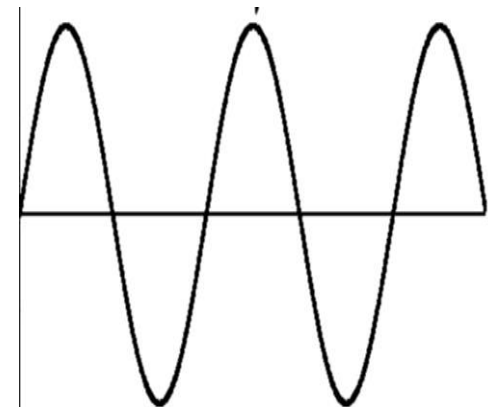
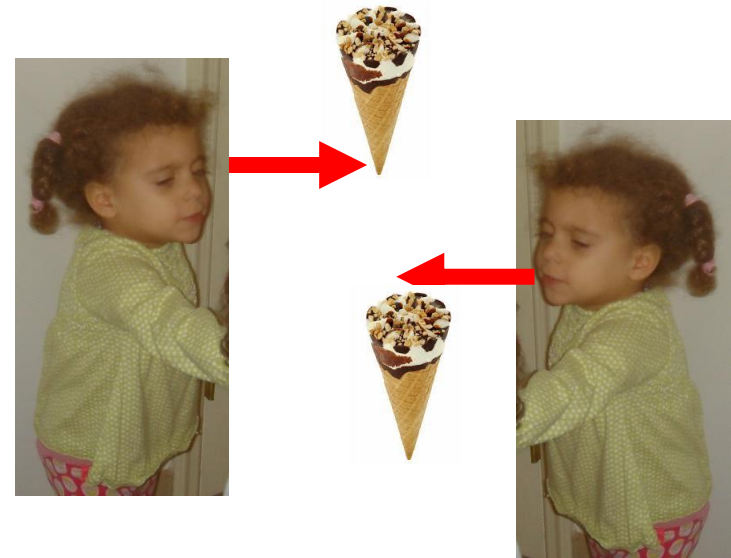
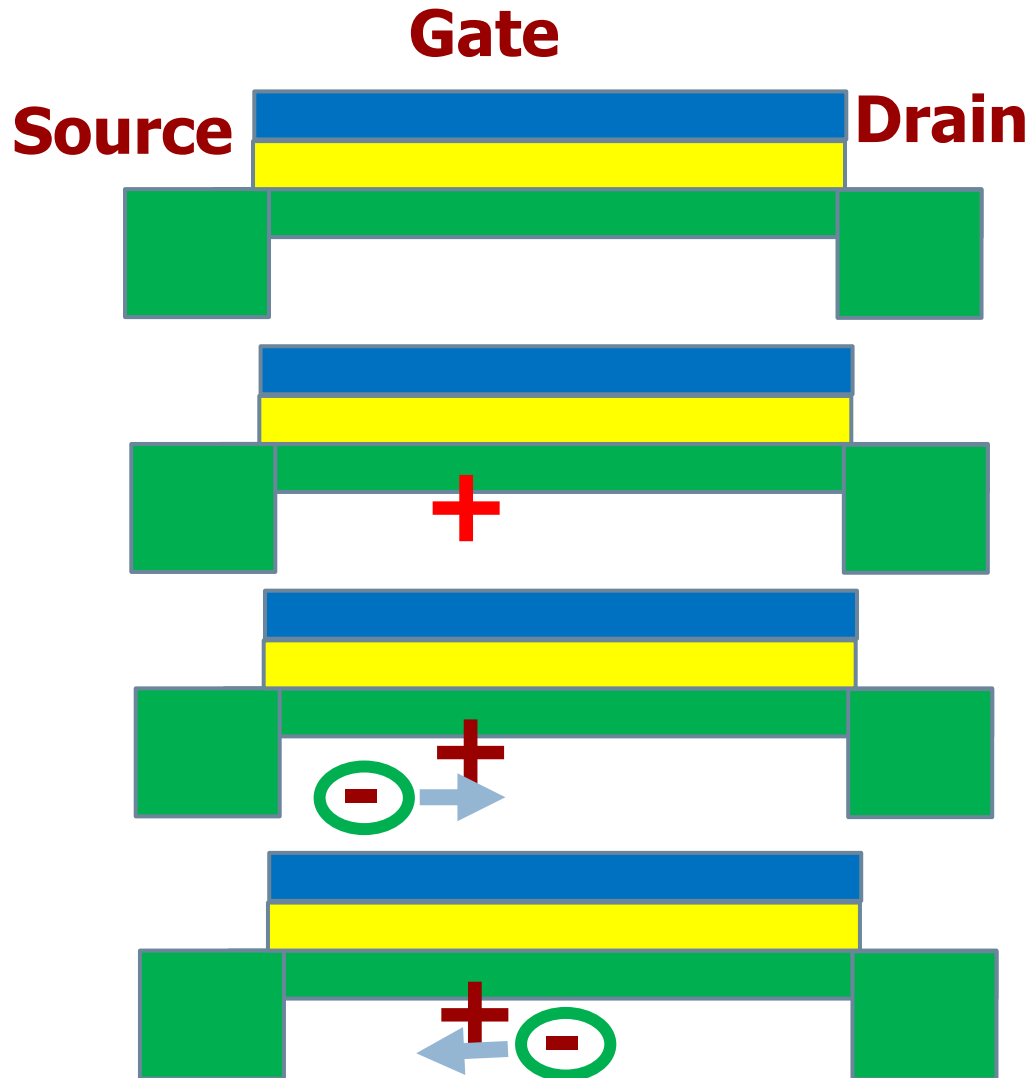
Interconnect Resistivity

13



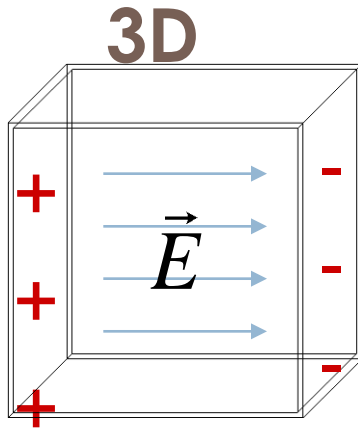
Plasma Waves

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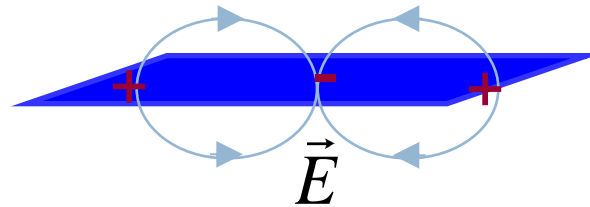


Dispersion of Plasma Waves

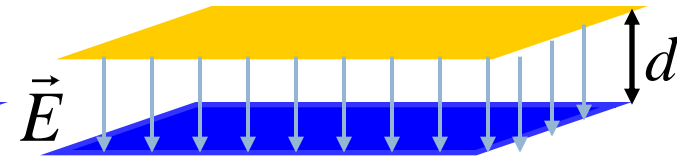
15



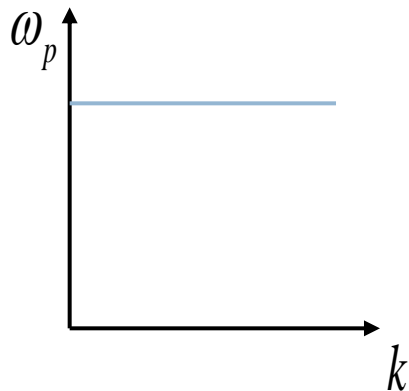
2D ungated



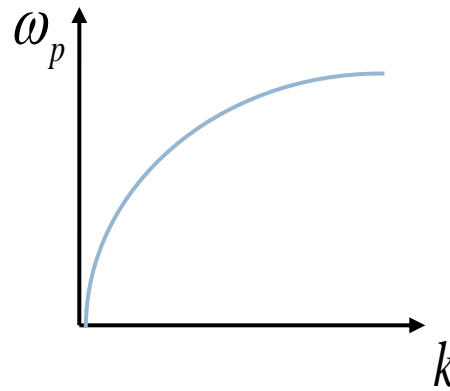
2D gated



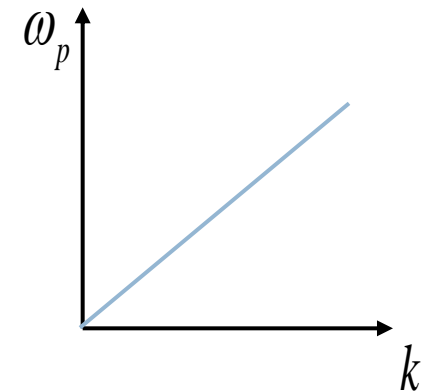
$$\omega_p = \sqrt{\frac{e^2 N_{3D}}{\epsilon \epsilon_0 m}}$$



$$\omega_p = \sqrt{\frac{e^2 N_{2D}}{2 \epsilon \epsilon_0 m} k}$$



$$\omega_p = \sqrt{\frac{e^2 N_{2D} d}{\epsilon \epsilon_0 m} k} \quad kd \ll 1$$

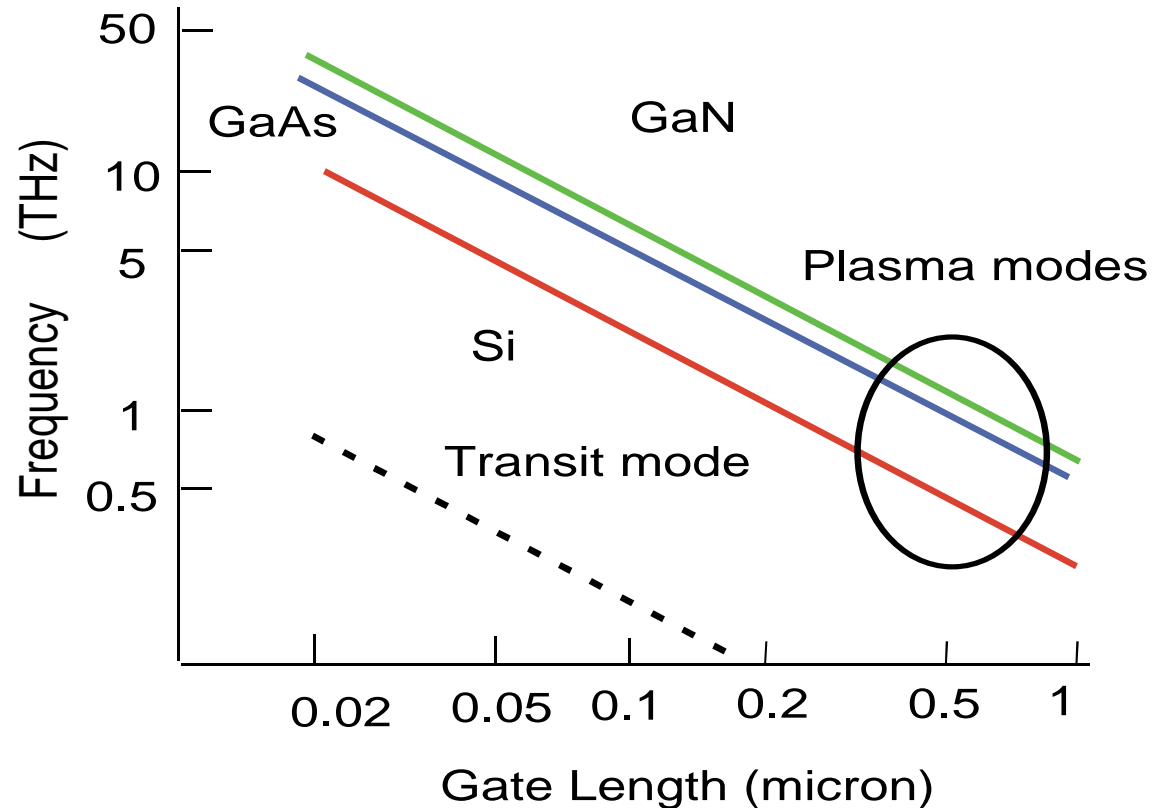




Plasma Waves in a Field Effect Transistors

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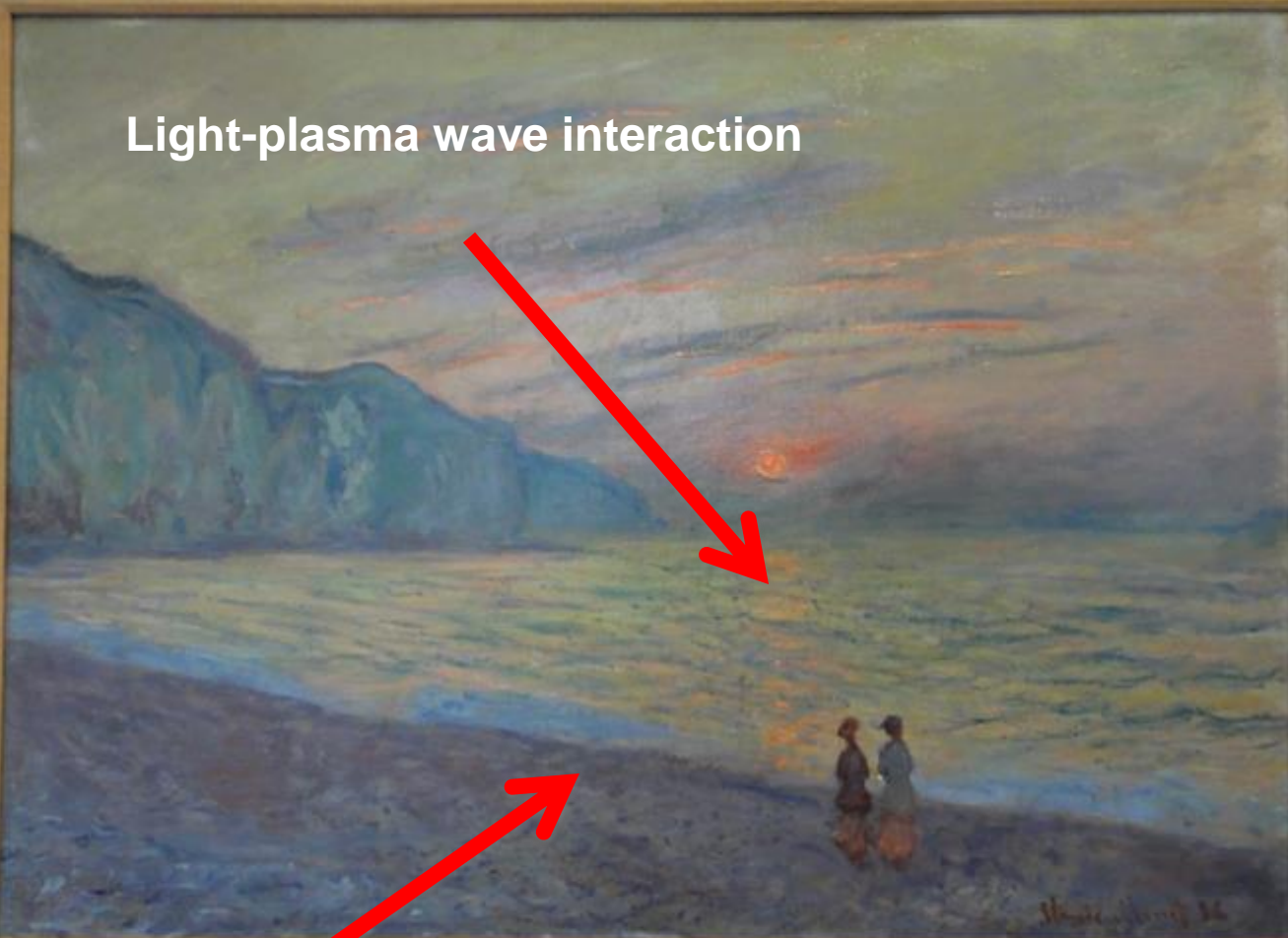
- Plasma frequency can be tuned by gate-to-channel voltage
- FET channel plays a role of a resonant cavity for plasma waves
- Plasma waves can propagate much faster than electrons



From V. Ryzhii and M.S. Shur, Plasma Wave Electronics Devices, ISDRS Digest, WP7-07-10, pp 200-201, Washington DC (2003)

Claude Monet Impressions of Sunset, Pourville (1882)

Light-plasma wave interaction



Effect of boundary conditions

Kreeger museum, Washington DC

Shock Plasma Waves (Hokusai 1760-1849)





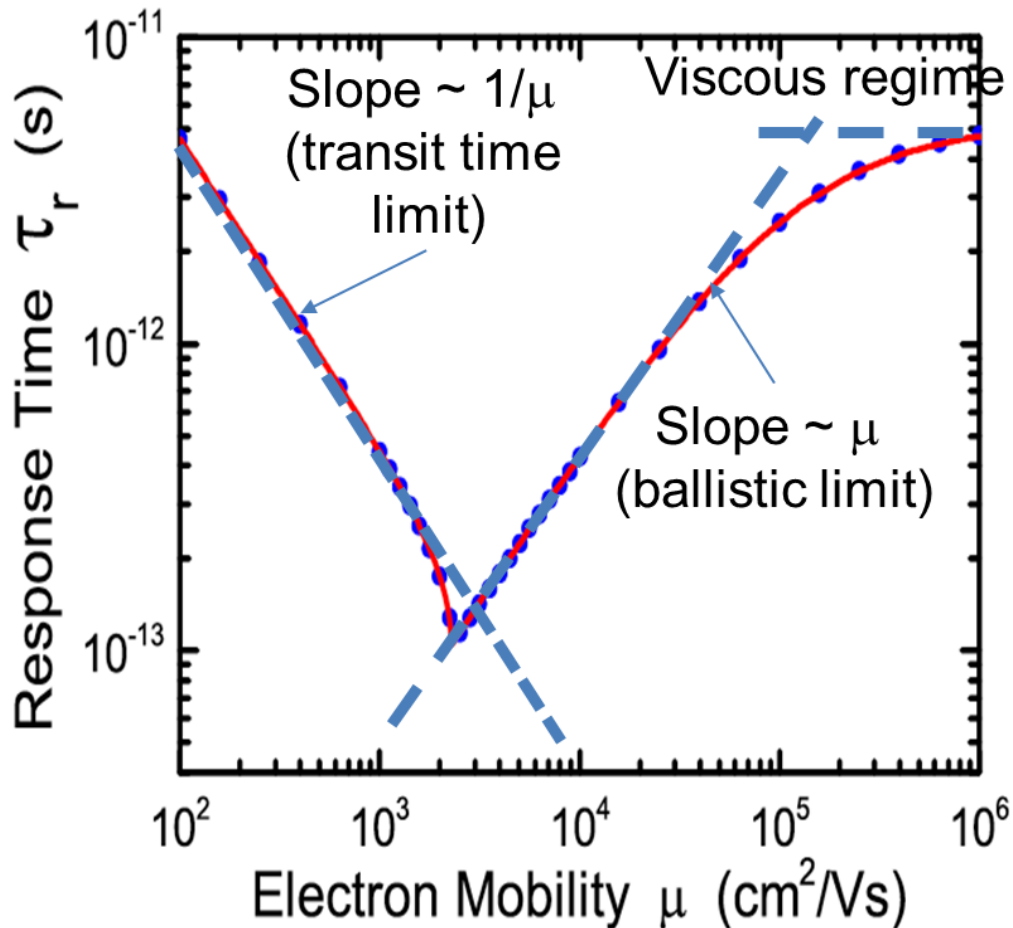
Plasma THz Electronics Advantages

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- **Small size (easy to fabricate arrays)**
- **High sensitivity**
- **Broad spectral range**
- **Band selectivity and tuneability**
- **Fast temporal response**
- **Si plasmonic FETs compatible with VLSI technology**

Physics of High Speed

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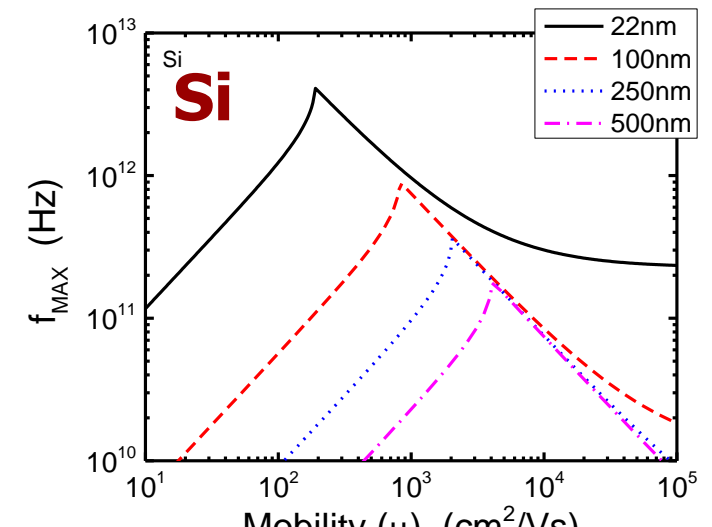
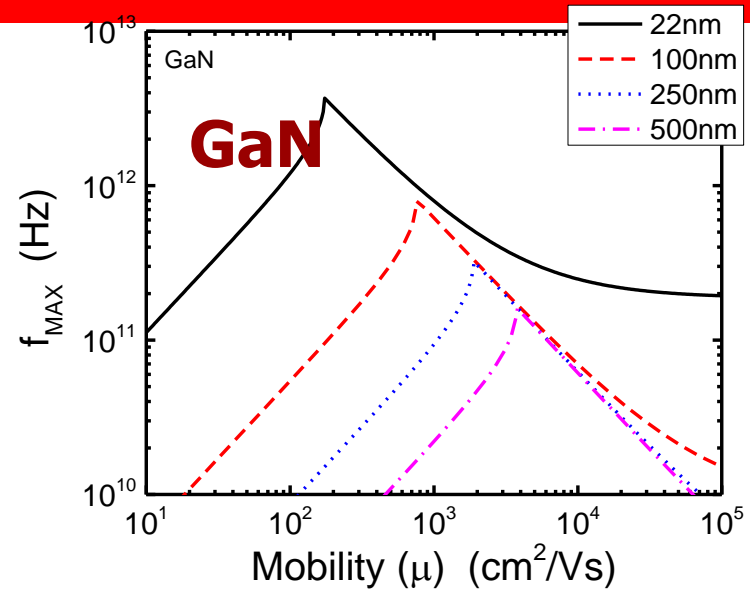
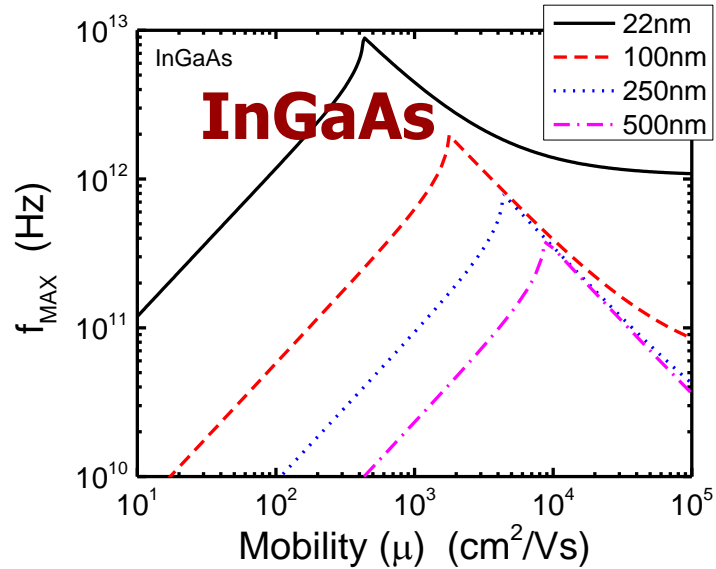
ELECTRON TRANSPORT

- Collision dominated
- Ballistic
- Viscous regime



Modulation frequency

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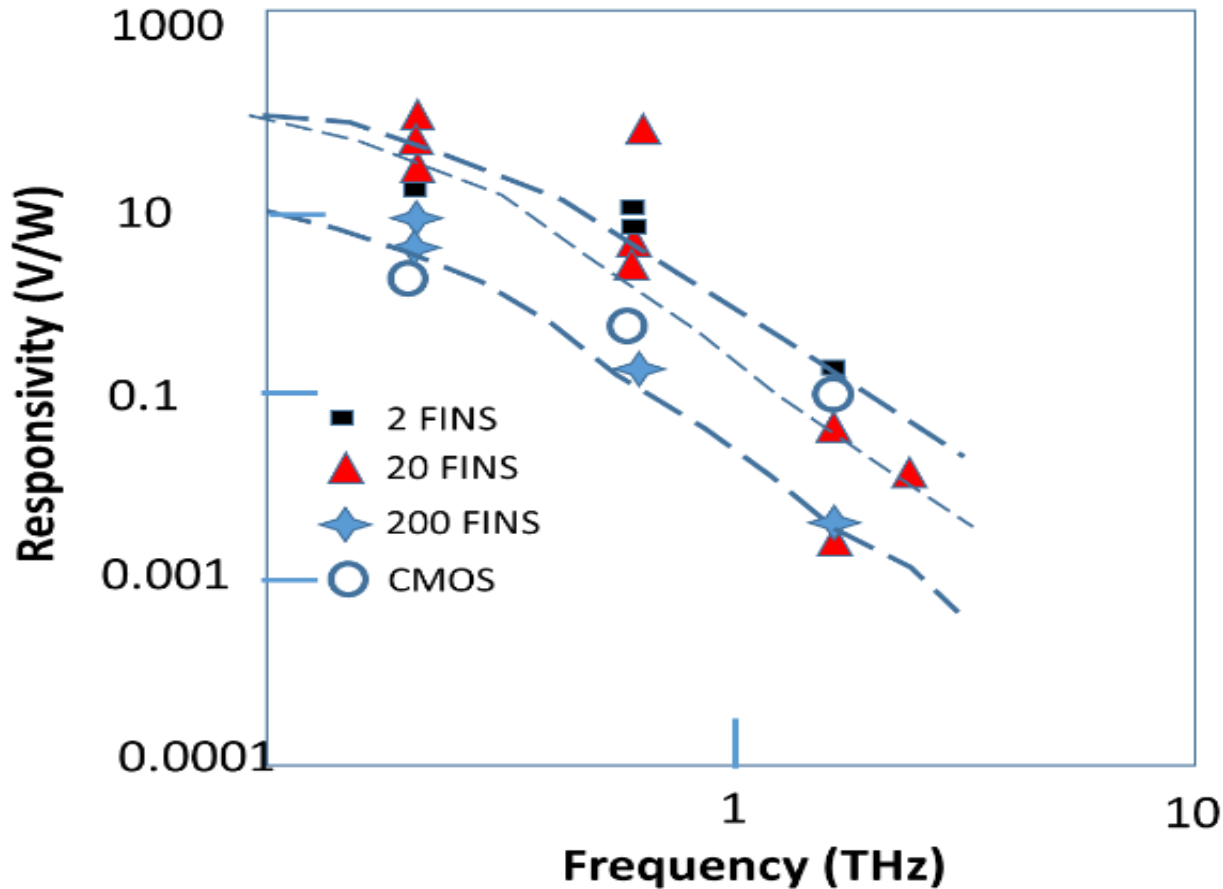


From M. Shur, G. Rupper and S. Rudin, " Ultimate limits for highest modulation frequency and shortest response time of field effect transistor ", Proc. SPIE 10194, Micro- and Nanotechnology Sensors, Systems, and Applications IX, 101942M (May 18, 2017); doi:10.1117/12.2261105; <http://dx.doi.org/10.1117/12.2261105>



Plasmonic detectors work up to 5 THz

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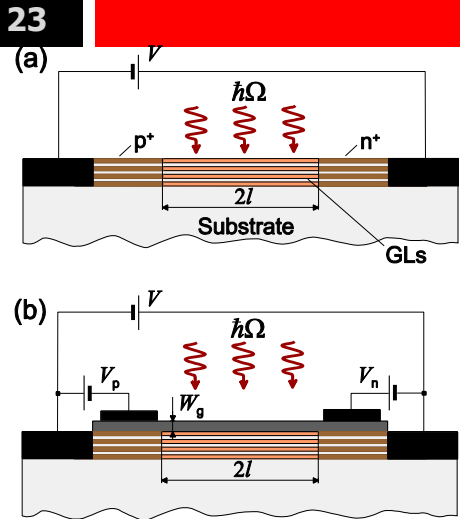


After W. Stillman, C. Donais, S. Rumyantsev, M. Shur, D. Veksler, C. Hobbs, C. Smith, G. Bersuker, W. Taylor and R. Jammy, Silicon FIN FETs as detectors of terahertz and sub-terahertz radiation, *International Journal of High Speed Electronics and Systems*, vol. 20, No. 1, pp. 27-42 March (2011)

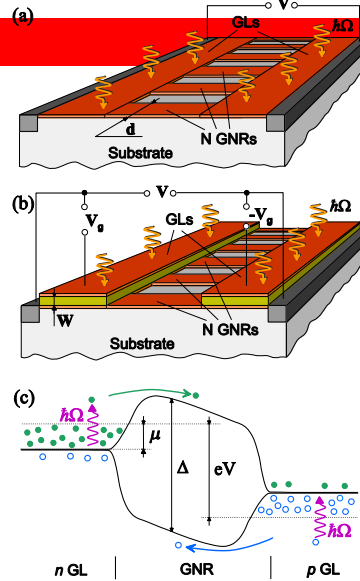
Graphene photodetectors concepts



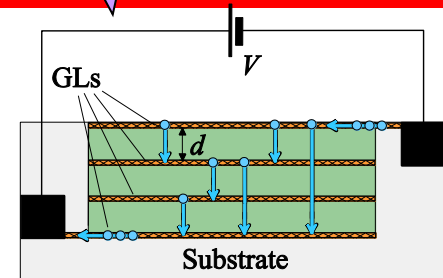
GL p-i-n photodiodes



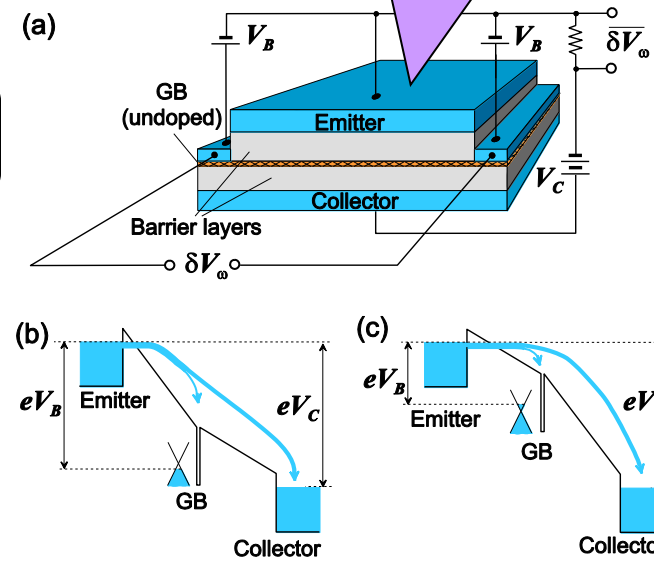
GNR hot-electron bolometers



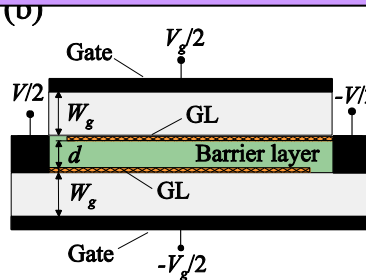
Vah der Waals hot-electron bolometer



Hot-electron transistor with GL base as plasmonic THz detector



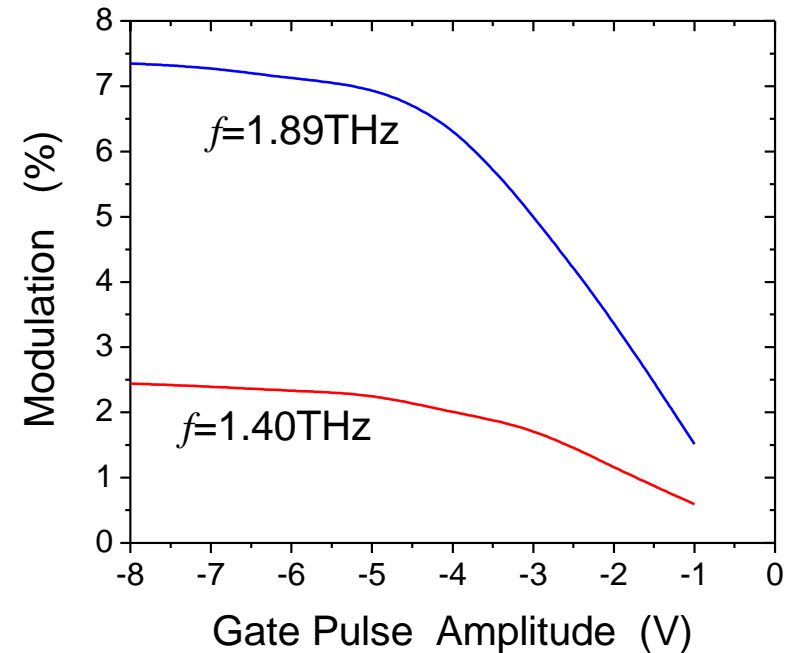
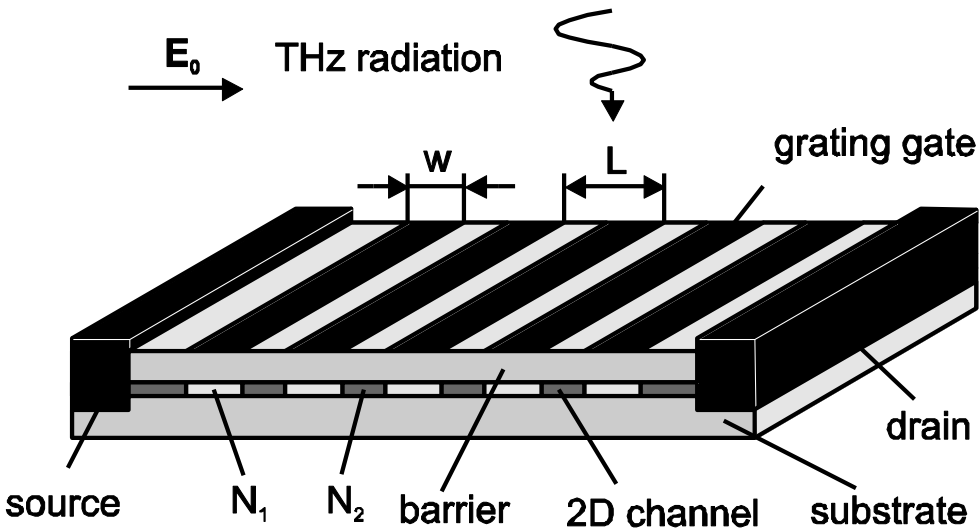
Interband double-GL photodetector



Double-GL plasmonic THz detectors

Modulator

24

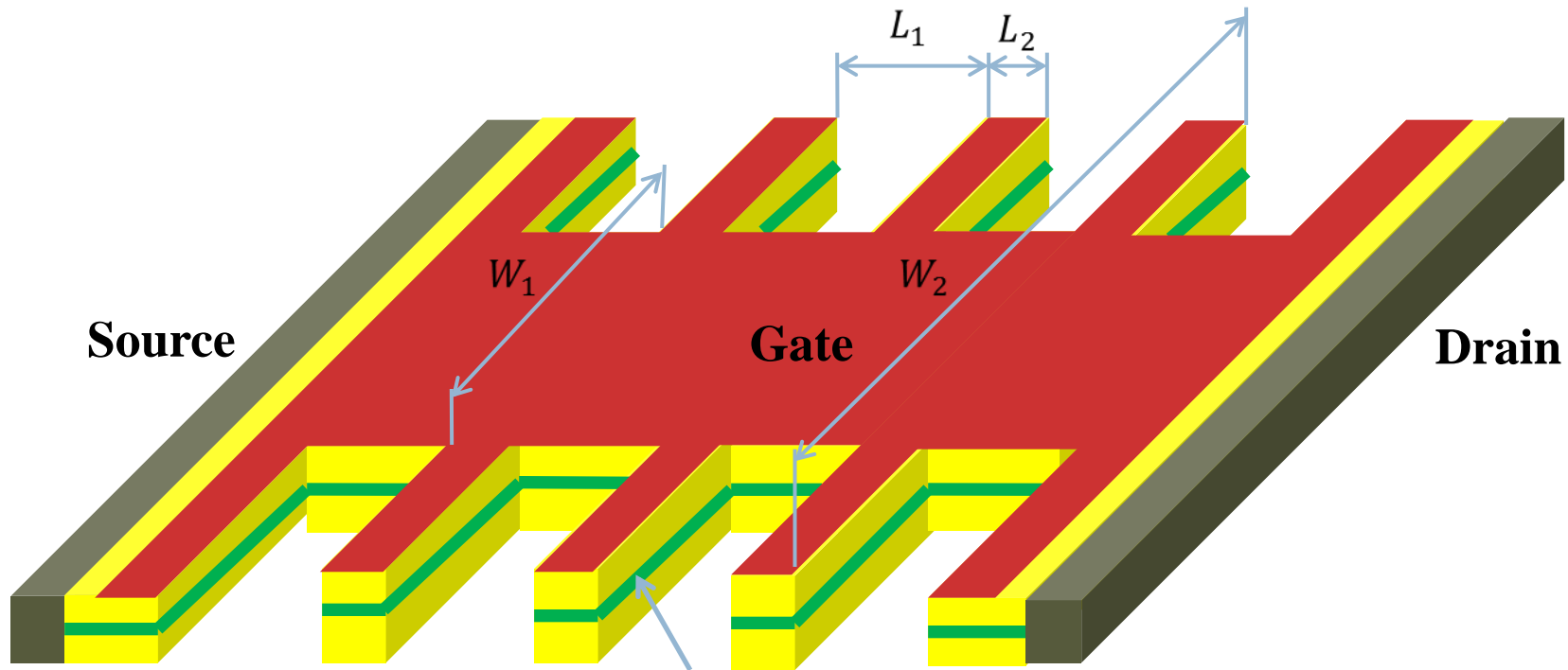


N. Pala, D. Veksler, A. Muravjov, W. Stillman, R. Gaska, and M. S. Shur, Resonant Detection and Modulation of Terahertz Radiation by 2DEG Plasmons in GaN Grating-Gate Structures, in Abstracts of IEEE Sensors Conference, Atlanta, GA, October 2007, pp. 291-292

Plasmonic Boom THz Source

25

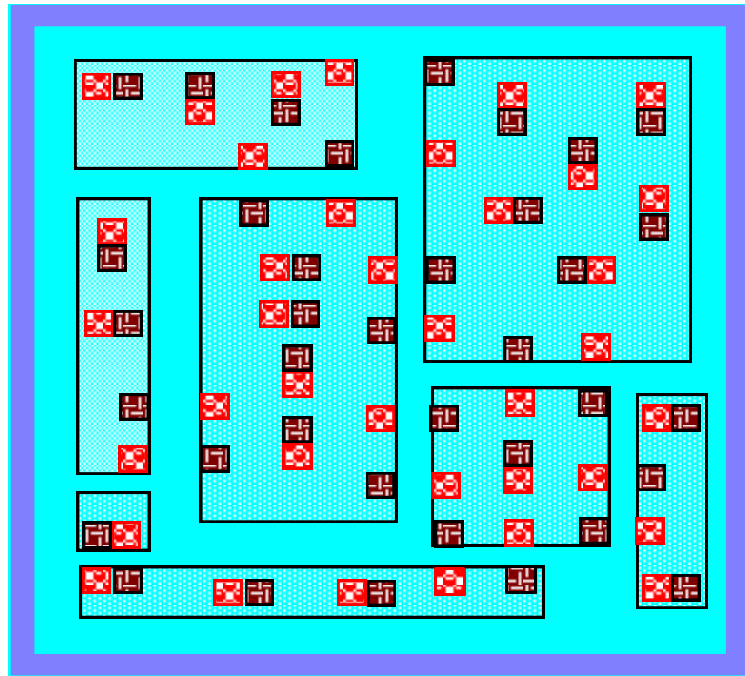
100 mW @ 1 THz




THz Communication on Nanoscale



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 Emitter  Detector  Chip Functional block

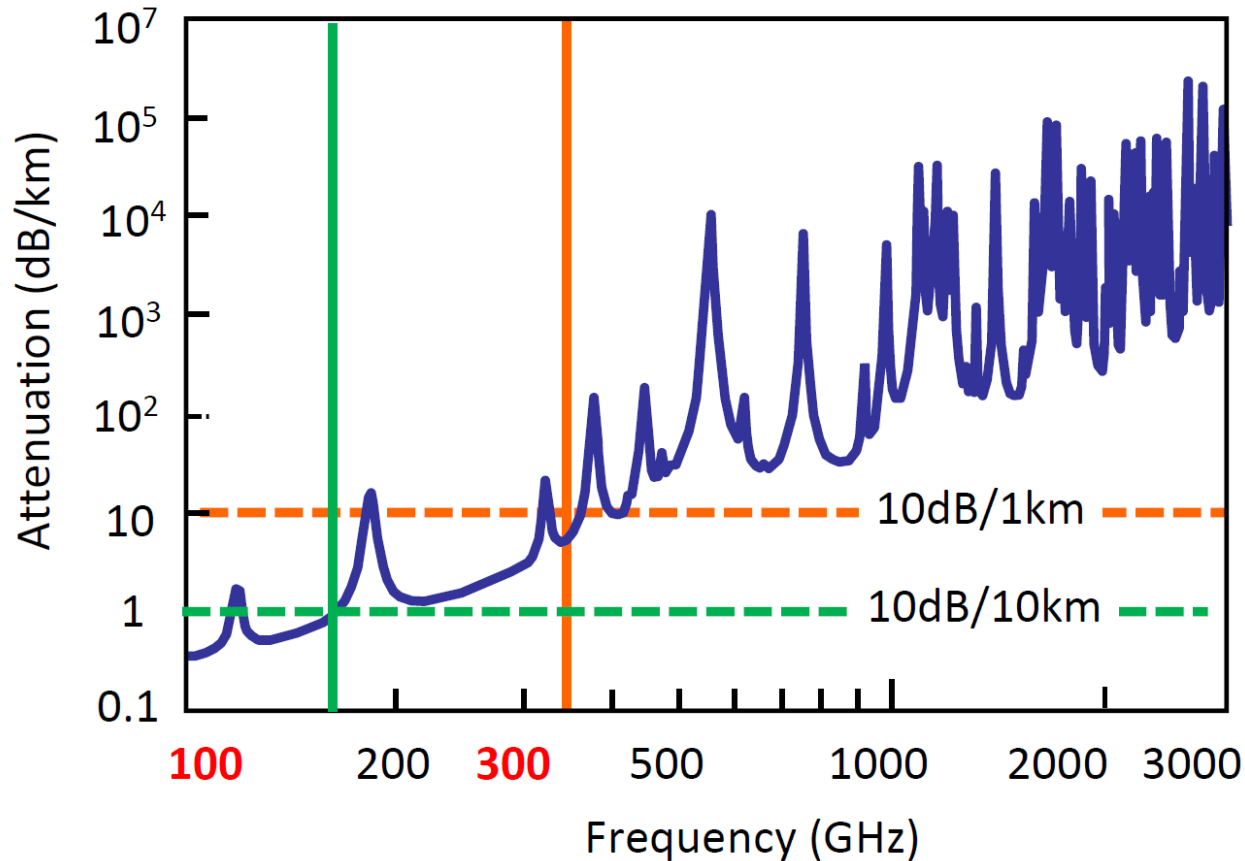
From Y. Deng and M. S. Shur, *Electron Mobility and Terahertz Detection using Silicon MOSFETs*, *Solid-State Electronics*, Vol. 47, Issue 9, pp. 1559-1563, September 2003

Large VLSI chip using terahertz emitter-detector pairs for wireless interconnect

THz attenuation in atmosphere



27



From Tadao Nagatsuma, Present and Future of Terahertz Communications "**TeraHertz: New opportunities for industry, EPFL, FEB 11-13, 2013**"



THz communication (0.1 THz to 30 THz)

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- ❑ **Goes through fog and dust**
- ❑ **Goes through walls**
- ❑ **LOS and NLOS with reflections**
- ❑ **Very secure**
- ❑ **Hard to jam**
- ❑ **Unique for next generation WLAN**
- ❑ **Unique for next generation WPAN (biomedical)**
- ❑ **Range from 1000's km in space to submicron communications on chip**
- ❑ **Data rates up to Tbps predicted**
- ❑ **Excellent for frequency spreading**



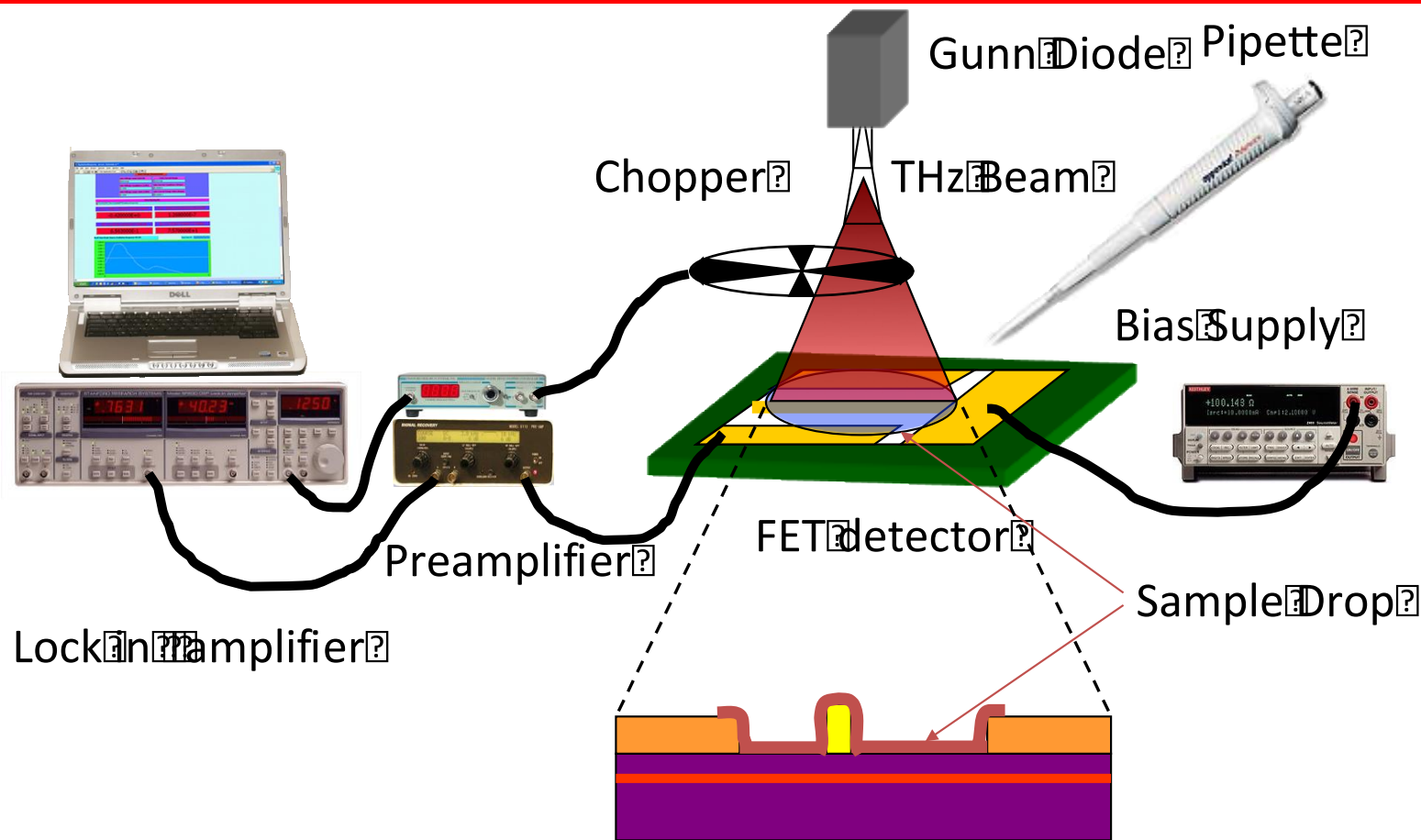
APPLICATIONS of THz SENSING TECHNOLOGY

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- ❑ Radio astronomy and Earth remote sensing
- ❑ Vehicle radars and compact radars
- ❑ Non-destructive VLSI testing
- ❑ Chemical sensors
- ❑ Explosive detection sensors
- ❑ Gasoline and oil quality testing
- ❑ Moisture content sensing
- ❑ Coating thickness control
- ❑ Film uniformity determination
- ❑ Structural integrity testing
- ❑ Medical diagnostics, sensing, and imaging
- ❑ Concealed weapons and object detection
- ❑ Detection of Chemical Warfare Agents

THz Sensing of Biofluids

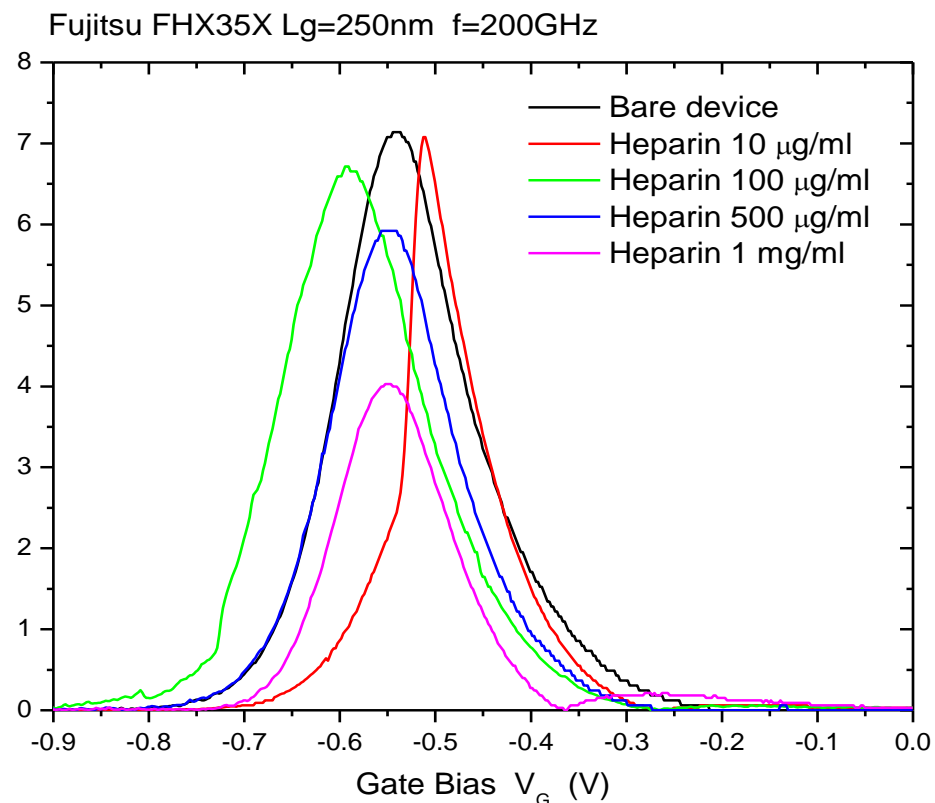
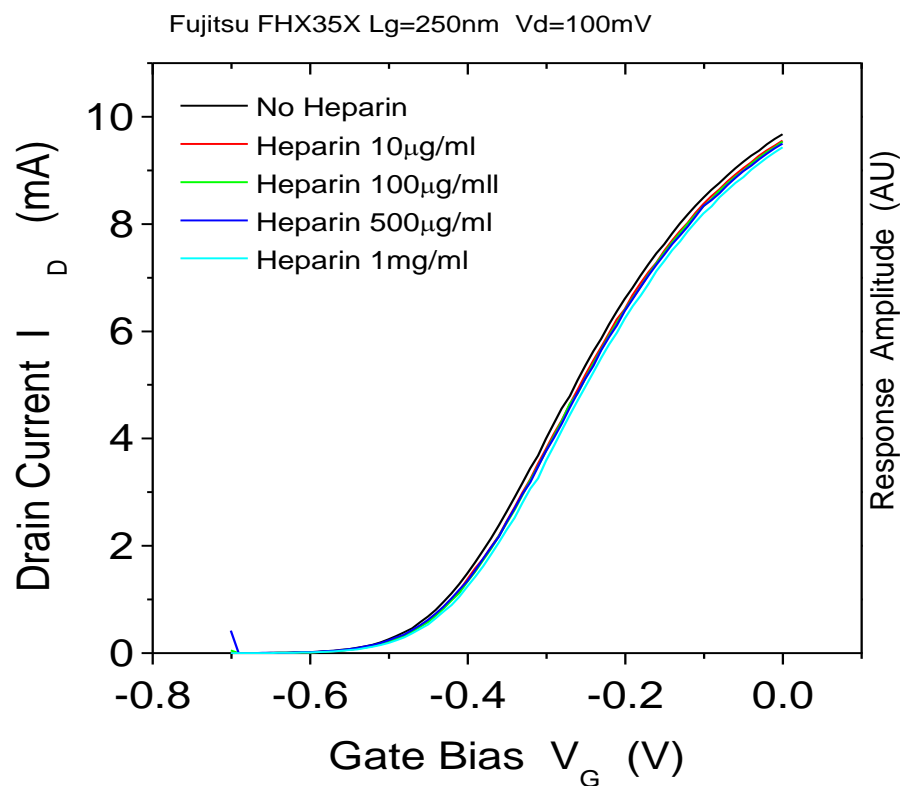
30





Transfer Characteristics With and Without Heparin and Response of the Plasma Wave Detector

31

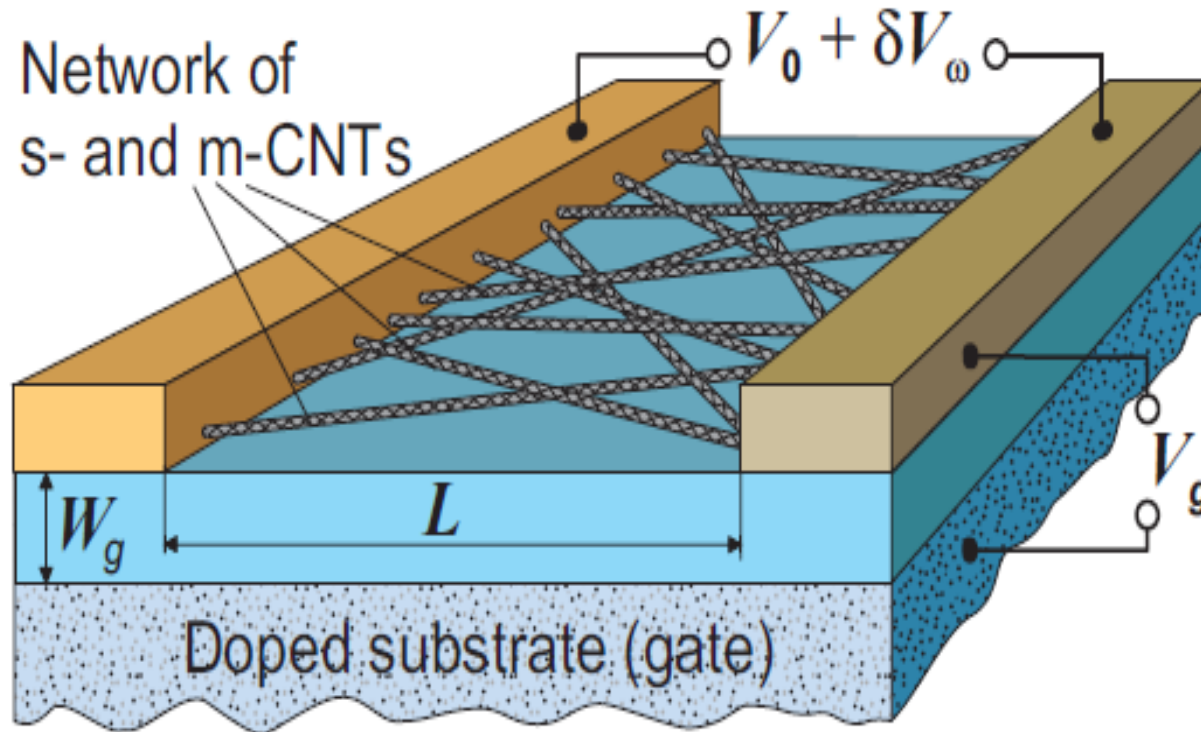


N. Pala and M. Shur, Plasmonic THz detectors for biodetection, Electronics Lett, Vol. 44, No24, p. 1391 (2008)
N. Pala, M. S. Shur, and R. Gaska, Plasma Wave-based THz Bio Detectors, presented at SPIE Optics East (2007)

Plasmonic sensor using 2D and 3D percolating CNTs



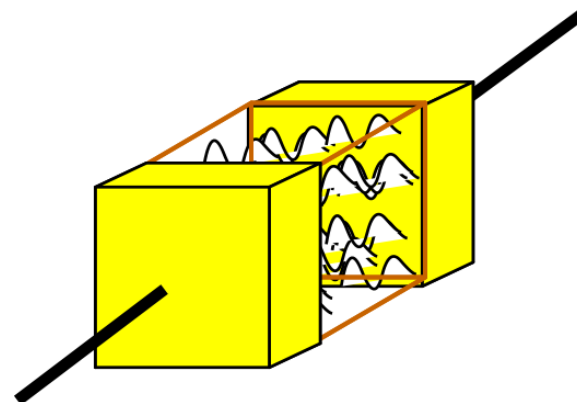
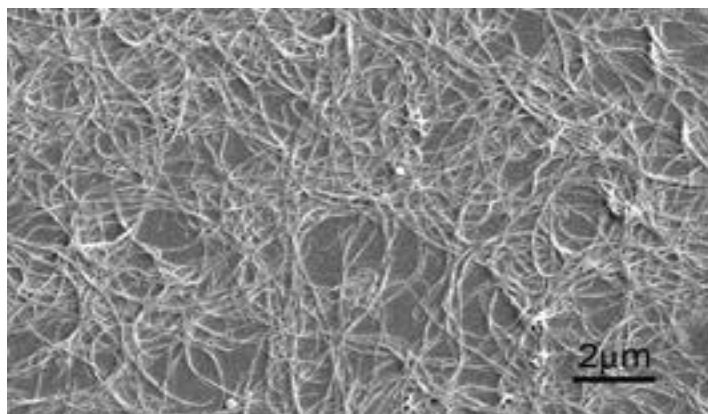
32



V. V. Ryzhii, T. Otsuji, M. Ryzhii, V. G. Leiman, G. Fedorov, G. N. Goltzman, I. A. Gayduchenko, N. Titova, D. Coquillat, D. But, W. Knap, V. Mitin, and M. S. Shur, "Two-dimensional plasmons in lateral carbon nanotube network structures and their effect on the terahertz radiation detection", *J. Appl. Phys.* 120(4) (2016) 044501.

CNT supercapacitors for IoT

33



M. Shur, 3D Carbon Nanotube Energy Storage and Sensors Devices and Systems, Provisional Patent Application, EFS ID: 29868227. Application Number: 62536092, Confirmation Number: 5173, July 24 (2017).

A. Vijayaraghavan, S. Kar, S. Romyantsev, A. Khanna, C. Soldano, N. Pala, R. Vajtai, O. Nalamasu, M. Shur, and P. Ajayan, Effect of Ambient Pressure on Resistance and Resistance Fluctuations in Single-Wall Carbon Nanotubes, J. Appl. Phys. 100, 024315 (2006),

Conclusions

- **Low power and band width requirements of IoT demand ultra small feature sizes**
- **Scaled interconnects become a dominant factor**
- **Plasma waves electronics approach could enable THz communication and sensing from nanoscale on chip to LPWA wireless network scale**
- **CNT, graphene and CNT supercapacitors integrated with Si VLSI have potential for IoT applications**
- **Future work: plasmonic THz sources**

Acknowledgment

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